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P. And H. B. 27/02
PATENT APPLICATION
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Application No.: 09/991,931

Filed: November 26, 2001

Docket No.: 103092.02

For: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING
THE SAME, CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

SUPPLEMENTAL PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 1-52 without prejudice to or disclaimer.

Please add new claims 53-73 as follows:

BI Sub 627
--53. A substrate having penetrating holes formed therein, the substrate having a conductive member adhered on one side thereof by an adhesive material over a particular region of the one side including the penetrating holes, a part of the adhesive material interposed in internal wall surfaces forming the penetrating holes.--

--54. The substrate as defined in claim 53, wherein a part of the adhesive material enters and exists within the penetrating holes.--

Sub 637
--55. A substrate having penetrating holes formed therein, the substrate having a conductive member directly formed over a particular region including the penetrating holes